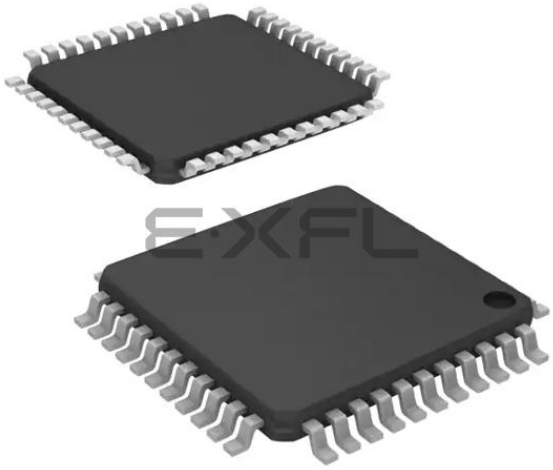

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	33
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	44-TQFP
Supplier Device Package	44-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx250f128d-v-pt

TABLE 2: PIC32MX2XX 28/36/44-PIN USB FAMILY FEATURES

Device	Pins	Program Memory (KB)(1)	Data Memory (KB)	Remappable Peripherals					Analog Comparators	USB On-The-Go (OTG)	I^2C	PMP	DMA Channels (Programmable/Dedicated)	CTMU	10-bit 1 Msps ADC (Channels)	RTCC	I/O Pins	JTAG	Packages
				Remappable Pins	Timers(2)/Capture/Compare	UART	SPI/I^2S	External Interrupts(3)											
PIC32MX210F016B	28	16+3	4	19	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	19	Y	SOIC, SSOP, SPDIP, QFN
PIC32MX210F016C	36	16+3	4	23	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	12	Y	25	Y	VTLA
PIC32MX210F016D	44	16+3	4	31	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	13	Y	33	Y	VTLA, TQFP, QFN
PIC32MX220F032B	28	32+3	8	19	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	19	Y	SOIC, SSOP, SPDIP, QFN
PIC32MX220F032C	36	32+3	8	23	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	12	Y	23	Y	VTLA
PIC32MX220F032D	44	32+3	8	31	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	13	Y	33	Y	VTLA, TQFP, QFN
PIC32MX230F064B	28	64+3	16	19	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	19	Y	SOIC, SSOP, SPDIP, QFN
PIC32MX230F064C	36	64+3	16	23	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	12	Y	23	Y	VTLA
PIC32MX230F064D	44	64+3	16	31	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	13	Y	33	Y	VTLA, TQFP, QFN
PIC32MX250F128B	28	128+3	32	19	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	19	Y	SOIC, SSOP, SPDIP, QFN
PIC32MX250F128C	36	128+3	32	23	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	12	Y	23	Y	VTLA
PIC32MX250F128D	44	128+3	32	31	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	13	Y	33	Y	VTLA, TQFP, QFN
PIC32MX230F256B	28	256+3	16	20	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	19	Y	SOIC, SSOP, SPDIP, QFN
PIC32MX230F256D	44	256+3	16	31	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	13	Y	33	Y	VTLA, TQFP, QFN
PIC32MX270F256B	28	256+3	64	19	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	9	Y	19	Y	SOIC, SSOP, SPDIP, QFN
PIC32MX270F256D	44	256+3	64	31	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	13	Y	33	Y	VTLA, TQFP, QFN
PIC32MX270F256DB(4)	44	256+3	64	31	5/5/5	2	2	5	3	Y	2	Y	4/2	Y	13	Y	33	Y	VTLA, TQFP, QFN

Note 1: This device features 3 KB of boot Flash memory.

2: Four out of five timers are remappable.

3: Four out of five external interrupts are remappable.

4: This PIC32 device is targeted to specific audio software packages that are tracked for licensing royalty purposes. All peripherals and electrical characteristics are identical to their corresponding base part numbers.

TABLE 6: PIN NAMES FOR 28-PIN USB DEVICES

28-PIN QFN (TOP VIEW)(1,2,3,4)

PIC32MX210F016B
PIC32MX220F032B
PIC32MX230F064B
PIC32MX230F256B
PIC32MX250F128B
PIC32MX270F256B

28 1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0	15	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1	16	VSS
3	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	17	VCAP
4	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	18	PGED2/RPB10/D+/CTED11/RB10
5	VSS	19	PGEC2/RPB11/D-/RB11
6	OSC1/CLKI/RPA2/RA2	20	VUSB3V3
7	OSC2/CLKO/RPA3/PMA0/RA3	21	AN11/RPB13/CTPLS/PMRD/RB13
8	SOSCI/RPB4/RB4	22	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14
9	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	23	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
10	VDD	24	AVSS
11	TMS/RPB5/USBID/RB5	25	AVDD
12	VBUS	26	$\overline{\text{MCLR}}$
13	TDI/RPB7/CTED3/PMD5/INT0/RB7	27	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0
14	TCK/RPB8/SCL1/CTED10/PMD4/RB8	28	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: Shaded pins are 5V tolerant.

TABLE 7: PIN NAMES FOR 36-PIN GENERAL PURPOSE DEVICES

36-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX110F016C
PIC32MX120F032C
PIC32MX130F064C
PIC32MX150F128C

36

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/RB2	19	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/RB3	20	RPC9/CTED7/RC9
3	PGED4(4)/AN6/RPC0/RC0	21	VSS
4	PGEC4(4)/AN7/RPC1/RC1	22	VCAP
5	VDD	23	VDD
6	VSS	24	PGED2/RPB10/CTED11/PMD2/RB10
7	OSC1/CLKI/RPA2/RA2	25	PGEC2/TMS/RPB11/PMD1/RB11
8	OSC2/CLKO/RPA3/PMA0/RA3	26	AN12/PMD0/RB12
9	SOSCI/RPB4/RB4	27	AN11/RPB13/CTPLS/PMRD/RB13
10	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	28	CVREFOUT/AN10/C3INB/RPB14/SCK1/CTED5/PMWR/RB14
11	RPC3/RC3	29	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
12	VSS	30	AVSS
13	VDD	31	AVDD
14	VDD	32	$\overline{\text{MCLR}}$
15	PGED3/RPB5/PMD7/RB5	33	VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/RA0
16	PGEC3/RPB6/PMD6/RB6	34	VREF-/CVREF-/AN1/RPA1/CTED2/RA1
17	TDI/RPB7/CTED3/PMD5/INT0/RB7	35	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/RB0
18	TCK/RPB8/SCL1/CTED10/PMD4/RB8	36	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/RB1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.
2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.
3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.
4: This pin function is not available on PIC32MX110F016C and PIC32MX120F032C devices.
5: Shaded pins are 5V tolerant.

TABLE 8: PIN NAMES FOR 36-PIN USB DEVICES

36-PIN VTLA (TOP VIEW)(1,2,3,5)

PIC32MX210F016C
PIC32MX220F032C
PIC32MX230F064C
PIC32MX250F128C

36

1

Pin #	Full Pin Name	Pin #	Full Pin Name
1	AN4/C1INB/C2IND/RPB2/SDA2/CTED13/PMD2/RB2	19	TDO/RPB9/SDA1/CTED4/PMD3/RB9
2	AN5/C1INA/C2INC/RTCC/RPB3/SCL2/PMWR/RB3	20	RPC9/CTED7/RC9
3	PGED4(4)/AN6/RPC0/RC0	21	VSS
4	PGEC4(4)/AN7/RPC1/RC1	22	VCAP
5	VDD	23	VDD
6	VSS	24	PGED2/RPB10/D+/CTED11/RB10
7	OSC1/CLKI/RPA2/RA2	25	PGEC2/RPB11/D-/RB11
8	OSC2/CLKO/RPA3/PMA0/RA3	26	VUSB3V3
9	SOSCI/RPB4/RB4	27	AN11/RPB13/CTPLS/PMRD/RB13
10	SOSCO/RPA4/T1CK/CTED9/PMA1/RA4	28	CVREFOUT/AN10/C3INB/RPB14/VBUSON/SCK1/CTED5/RB14
11	AN12/RPC3/RC3	29	AN9/C3INA/RPB15/SCK2/CTED6/PMCS1/RB15
12	VSS	30	AVSS
13	VDD	31	AVDD
14	VDD	32	$\overline{\text{MCLR}}$
15	TMS/RPB5/USBID/RB5	33	PGED3/VREF+/CVREF+/AN0/C3INC/RPA0/CTED1/PMD7/RA0
16	VBUS	34	PGEC3/VREF-/CVREF-/AN1/RPA1/CTED2/PMD6/RA1
17	TDI/RPB7/CTED3/PMD5/INT0/RB7	35	PGED1/AN2/C1IND/C2INB/C3IND/RPB0/PMD0/RB0
18	TCK/RPB8/SCL1/CTED10/PMD4/RB8	36	PGEC1/AN3/C1INC/C2INA/RPB1/CTED12/PMD1/RB1

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 11.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RCx) can be used as a change notification pin (CNAx-CNCx). See **Section 11.0 "I/O Ports"** for more information.

3: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

4: This pin function is not available on PIC32MX210F016C and PIC32MX120F032C devices.

5: Shaded pins are 5V tolerant.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
OC1	PPS	PPS	PPS	PPS	O	—	Output Compare Output 1
OC2	PPS	PPS	PPS	PPS	O	—	Output Compare Output 2
OC3	PPS	PPS	PPS	PPS	O	—	Output Compare Output 3
OC4	PPS	PPS	PPS	PPS	O	—	Output Compare Output 4
OC5	PPS	PPS	PPS	PPS	O	—	Output Compare Output 5
OCFA	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault A Input
OCFB	PPS	PPS	PPS	PPS	I	ST	Output Compare Fault B Input
INT0	13	16	17	43	I	ST	External Interrupt 0
INT1	PPS	PPS	PPS	PPS	I	ST	External Interrupt 1
INT2	PPS	PPS	PPS	PPS	I	ST	External Interrupt 2
INT3	PPS	PPS	PPS	PPS	I	ST	External Interrupt 3
INT4	PPS	PPS	PPS	PPS	I	ST	External Interrupt 4
RA0	27	2	33	19	I/O	ST	PORTA is a bidirectional I/O port
RA1	28	3	34	20	I/O	ST	
RA2	6	9	7	30	I/O	ST	
RA3	7	10	8	31	I/O	ST	
RA4	9	12	10	34	I/O	ST	
RA7	—	—	—	13	I/O	ST	
RA8	—	—	—	32	I/O	ST	
RA9	—	—	—	35	I/O	ST	
RA10	—	—	—	12	I/O	ST	
RB0	1	4	35	21	I/O	ST	PORTB is a bidirectional I/O port
RB1	2	5	36	22	I/O	ST	
RB2	3	6	1	23	I/O	ST	
RB3	4	7	2	24	I/O	ST	
RB4	8	11	9	33	I/O	ST	
RB5	11	14	15	41	I/O	ST	
RB6	12(2)	15(2)	16(2)	42(2)	I/O	ST	
RB7	13	16	17	43	I/O	ST	
RB8	14	17	18	44	I/O	ST	
RB9	15	18	19	1	I/O	ST	
RB10	18	21	24	8	I/O	ST	
RB11	19	22	25	9	I/O	ST	
RB12	20(2)	23(2)	26(2)	10(2)	I/O	ST	
RB13	21	24	27	11	I/O	ST	
RB14	22	25	28	14	I/O	ST	
RB15	23	26	29	15	I/O	ST	

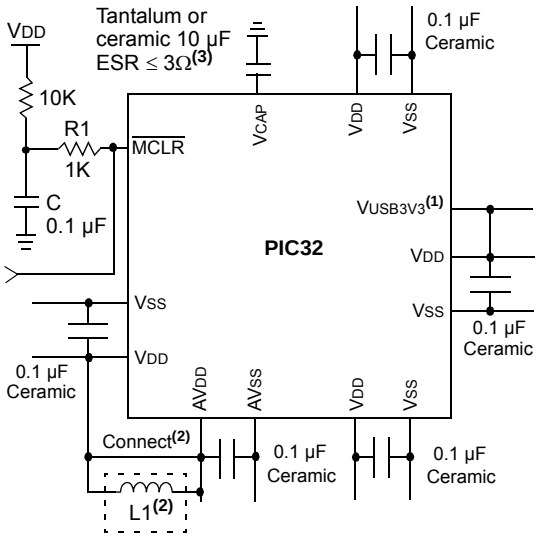
Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: If the USB module is not used, this pin must be connected to VDD.

2: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 3Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

1: Aluminum or electrolytic capacitors should not be used. ESR ≤ 3Ω from -40ºC to 125ºC @ SYSCLK frequency (i.e., MIPS).

2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (3 ohm) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **30.0 "Electrical Characteristics"** for additional information on CEFC specifications.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

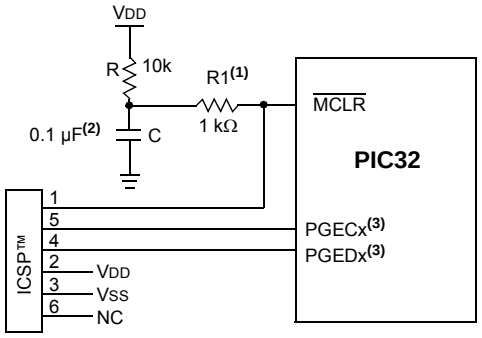
- Device Reset
- Device programming and debugging

Pulling The MCLR pin low generates a device Reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components illustrated in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: 470Ω ≤ R1 ≤ 1Ω will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met without interfering with the Debug/Programmer tools.

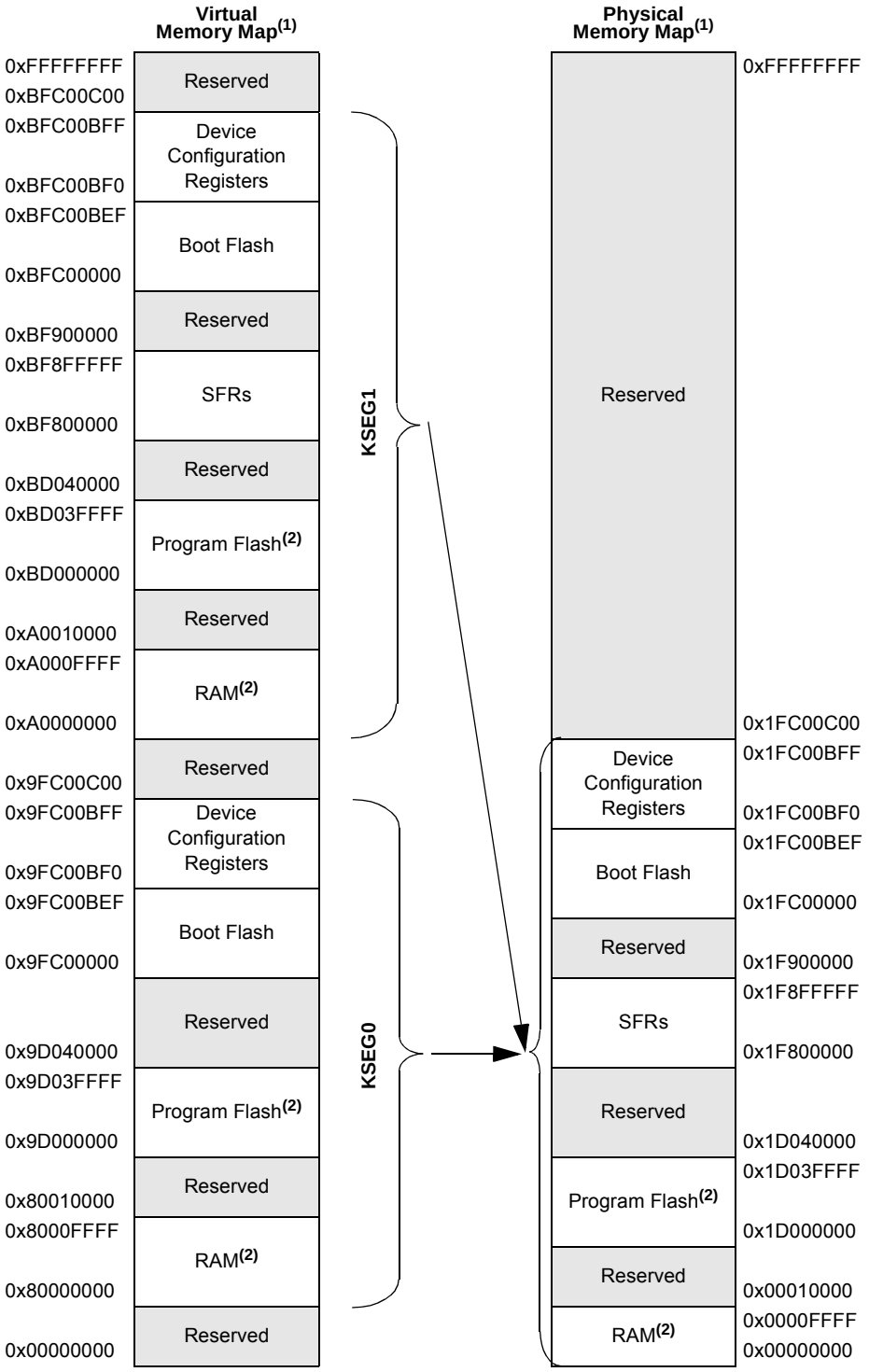
2: The capacitor can be sized to prevent unintentional Resets from brief glitches or to extend the device Reset period during POR.

3: No pull-ups or bypass capacitors are allowed on active debug/program PGECx/PGEDx pins.

2.5 ICSP Pins

The PGECx and PGEDx pins are used for ICSP and debugging purposes. It is recommended to keep the trace length between the ICSP connector and the ICSP pins on the device as short as possible. If the ICSP connector is expected to experience an ESD event, a series resistor is recommended, with the value in the range of a few tens of Ohms, not to exceed 100 Ohms.

FIGURE 4-5: MEMORY MAP ON RESET FOR PIC32MX170/270 DEVICES (64 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

REGISTER 7-6: IPCx: INTERRUPT PRIORITY CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	IP03<2:0>			IS03<1:0>	
23:16	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	IP02<2:0>			IS02<1:0>	
15:8	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	IP01<2:0>			IS01<1:0>	
7:0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	IP00<2:0>			IS00<1:0>	

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-29 **Unimplemented:** Read as '0'

bit 28-26 **IP03<2:0>:** Interrupt Priority bits
- 111 = Interrupt priority is 7
- •
- •
- •
- 010 = Interrupt priority is 2
- 001 = Interrupt priority is 1
- 000 = Interrupt is disabled

bit 25-24 **IS03<1:0>:** Interrupt Subpriority bits
- 11 = Interrupt subpriority is 3
- 10 = Interrupt subpriority is 2
- 01 = Interrupt subpriority is 1
- 00 = Interrupt subpriority is 0

bit 23-21 **Unimplemented:** Read as '0'

bit 20-18 **IP02<2:0>:** Interrupt Priority bits
- 111 = Interrupt priority is 7
- •
- •
- •
- 010 = Interrupt priority is 2
- 001 = Interrupt priority is 1
- 000 = Interrupt is disabled

bit 17-16 **IS02<1:0>:** Interrupt Subpriority bits
- 11 = Interrupt subpriority is 3
- 10 = Interrupt subpriority is 2
- 01 = Interrupt subpriority is 1
- 00 = Interrupt subpriority is 0

bit 15-13 **Unimplemented:** Read as '0'

bit 12-10 **IP01<2:0>:** Interrupt Priority bits
- 111 = Interrupt priority is 7
- •
- •
- •
- 010 = Interrupt priority is 2
- 001 = Interrupt priority is 1
- 000 = Interrupt is disabled

Note: This register represents a generic definition of the IPCx register. Refer to Table 7-1 for the exact bit definitions.

REGISTER 9-12: DCHxSSIZ: DMA CHANNEL 'x' SOURCE SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHSSIZ<15:0>:** Channel Source Size bits

1111111111111111 = 65,535 byte source size
.
.
.
0000000000000010 = 2 byte source size
0000000000000001 = 1 byte source size
0000000000000000 = 65,536 byte source size

REGISTER 9-13: DCHxDSIZ: DMA CHANNEL 'x' DESTINATION SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHDSIZ<15:0>:** Channel Destination Size bits

1111111111111111 = 65,535 byte destination size
.
.
.
0000000000000010 = 2 byte destination size
0000000000000001 = 1 byte destination size
0000000000000000 = 65,536 byte destination size

REGISTER 10-6: U1IR: USB INTERRUPT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R/WC-0, HS	R-0	R/WC-0, HS
	STALLIF	ATTACHIF(1)	RESUMEIF(2)	IDLEIF	TRNIF(3)	SOFIF	UERRIF(4)	URSTIF(5) / DETACHIF(6)

Legend:	WC = Write '1' to clear	HS = Hardware Settable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7 **STALLIF:** STALL Handshake Interrupt bit
1 = In Host mode a STALL handshake was received during the handshake phase of the transaction
In Device mode a STALL handshake was transmitted during the handshake phase of the transaction
0 = STALL handshake has not been sent

bit 6 **ATTACHIF:** Peripheral Attach Interrupt bit(1)
1 = Peripheral attachment was detected by the USB module
0 = Peripheral attachment was not detected

bit 5 **RESUMEIF:** Resume Interrupt bit(2)
1 = K-State is observed on the D+ or D- pin for 2.5 µs
0 = K-State is not observed

bit 4 **IDLEIF:** Idle Detect Interrupt bit
1 = Idle condition detected (constant Idle state of 3 ms or more)
0 = No Idle condition detected

bit 3 **TRNIF:** Token Processing Complete Interrupt bit(3)
1 = Processing of current token is complete; a read of the U1STAT register will provide endpoint information
0 = Processing of current token not complete

bit 2 **SOFIF:** SOF Token Interrupt bit
1 = SOF token received by the peripheral or the SOF threshold reached by the host
0 = SOF token was not received nor threshold reached

bit 1 **UERRIF**: USB Error Condition Interrupt bit(4)
1 = Unmasked error condition has occurred
0 = Unmasked error condition has not occurred

bit 0 **URSTIF:** USB Reset Interrupt bit (Device mode)(5)
1 = Valid USB Reset has occurred
0 = No USB Reset has occurred
DETACHIF: USB Detach Interrupt bit (Host mode)(6)
1 = Peripheral detachment was detected by the USB module
0 = Peripheral detachment was not detected

Note 1: This bit is valid only if the HOSTEN bit is set (see Register 10-11), there is no activity on the USB for 2.5 µs, and the current bus state is not SE0.
2: When not in Suspend mode, this interrupt should be disabled.
3: Clearing this bit will cause the STAT FIFO to advance.
4: Only error conditions enabled through the U1EIE register will set this bit.
5: Device mode.
6: Host mode.

TABLE 11-6: PERIPHERAL PIN SELECT INPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FA54	U1CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U1CTSR<3:0>				0000
FA58	U2RXR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U2RXR<3:0>				0000
FA5C	U2CTSR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	U2CTSR<3:0>				0000
FA84	SDI1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI1R<3:0>				0000
FA88	SS1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS1R<3:0>				0000
FA90	SDI2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SDI2R<3:0>				0000
FA94	SS2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	SS2R<3:0>				0000
FAB8	REFCLKIR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	REFCLKIR<3:0>				0000

TABLE 11-7: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP (CONTINUED)

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FB8C	RPC8R(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPC8<3:0>				0000
FB90	RPC9R(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPC9<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register is only available on 44-pin devices.
2: This register is only available on PIC32MX1XX devices.
3: This register is only available on 36-pin and 44-pin devices.

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>:** Alarm Repeat Counter Value bits(2)

11111111 = Alarm will trigger 256 times
•
•
•
00000000 = Alarm will trigger one time
The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

Note 1: Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.

2: This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.

3: This assumes a CPU read will execute in less than 32 PBCLKs.

Note:	This register is reset only on a Power-on Reset (POR).

NOTES:

29.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

29.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

29.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

29.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

29.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

TABLE 30-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
	VIL	**Input Low Voltage**					
DI10		I/O Pins with PMP	VSS	—	0.15 VDD	V	
		I/O Pins	VSS	—	0.2 VDD	V	
DI18		SDAx, SCLx	VSS	—	0.3 VDD	V	SMBus disabled **(Note 4)**
DI19		SDAx, SCLx	VSS	—	0.8	V	SMBus enabled **(Note 4)**
	VIH	**Input High Voltage**					
DI20		I/O Pins not 5V-tolerant(5)	0.65 VDD	—	VDD	V	**(Note 4,6)**
		I/O Pins 5V-tolerant with PMP(5)	0.25 VDD + 0.8V	—	5.5	V	**(Note 4,6)**
		I/O Pins 5V-tolerant(5)	0.65 VDD	—	5.5	V	
DI28		SDAx, SCLx	0.65 VDD	—	5.5	V	SMBus disabled **(Note 4,6)**
DI29		SDAx, SCLx	2.1	—	5.5	V	SMBus enabled, 2.3V ≤ VPIN ≤ 5.5 **(Note 4,6)**
DI30	ICNPU	**Change Notification Pull-up Current**	—	—	-50	µA	VDD = 3.3V, VPIN = VSS **(Note 3,6)**
DI31	ICNPD	**Change Notification Pull-down Current(4)**	—	—	-50	µA	VDD = 3.3V, VPIN = VDD
	IIL	**Input Leakage Current (Note 3)**					
DI50		I/O Ports	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI51		Analog Input Pins	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, Pin at high-impedance
DI55		$\overline{\text{MCLR}}$(2)	—	—	±1	µA	VSS ≤ VPIN ≤ VDD
DI56		OSC1	—	—	±1	µA	VSS ≤ VPIN ≤ VDD, XT and HS modes

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: This parameter is characterized, but not tested in manufacturing.

5: See the **"Pin Diagrams"** section for the 5V-tolerant pins.

6: The VIH specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic "high" internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External "input" logic inputs that require a pull-up source, to guarantee the minimum VIH of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

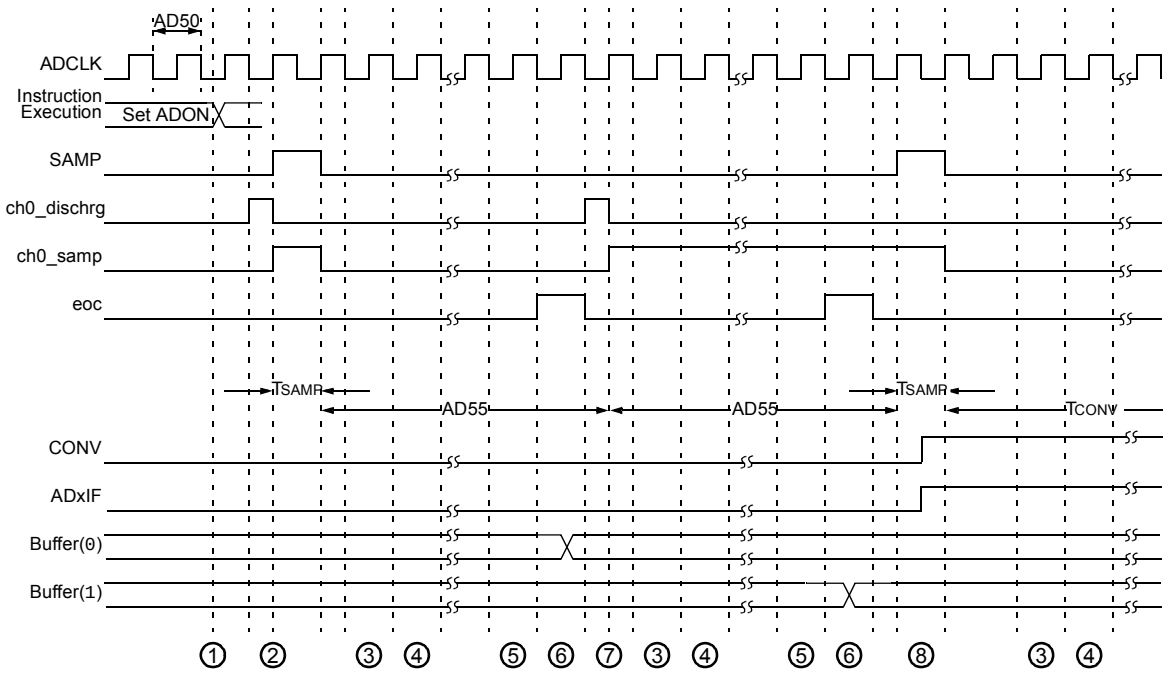
AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	—
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode **(Note 2)**	0	0.3	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	µs	After this period, the first clock pulse is generated
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPB * (BRG + 2)	—	µs	—
			400 kHz mode	TPB * (BRG + 2)	—	µs	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TPB * (BRG + 2)	—	ns	—
			400 kHz mode	TPB * (BRG + 2)	—	ns	
			1 MHz mode **(Note 2)**	TPB * (BRG + 2)	—	ns	

Note 1: BRG is the value of the I^2C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets ADxCON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 17. "10-bit Analog-to-Digital Converter (ADC)"** (DS60001104).

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

FIGURE 32-6: TYPICAL FRC FREQUENCY @ VDD = 3.3V

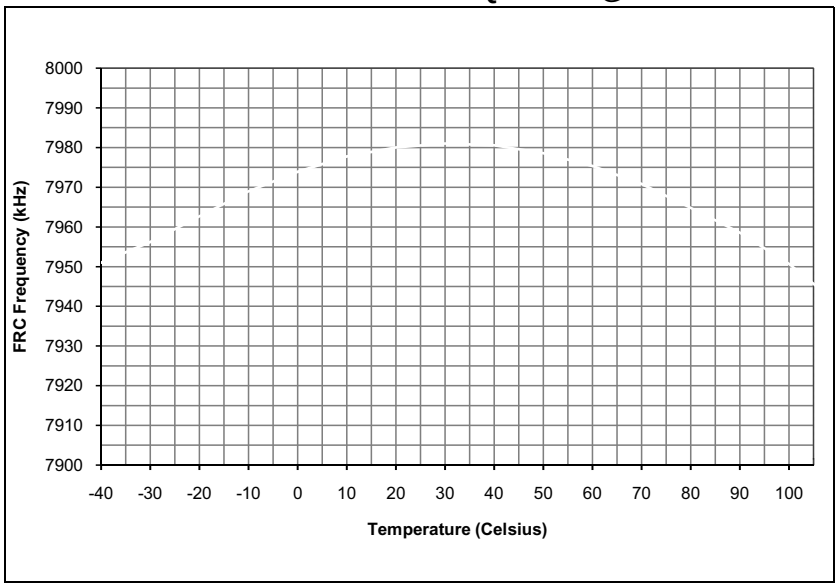


FIGURE 32-7: TYPICAL LPRC FREQUENCY @ VDD = 3.3V

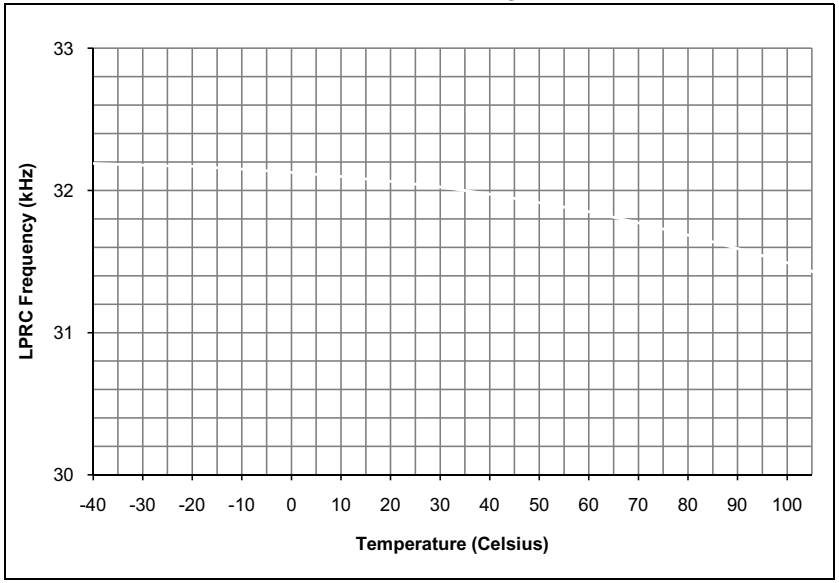
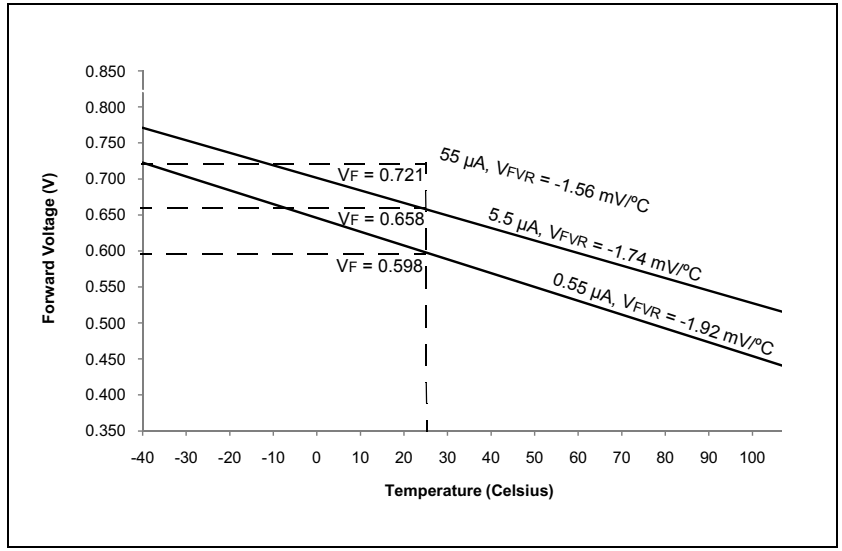
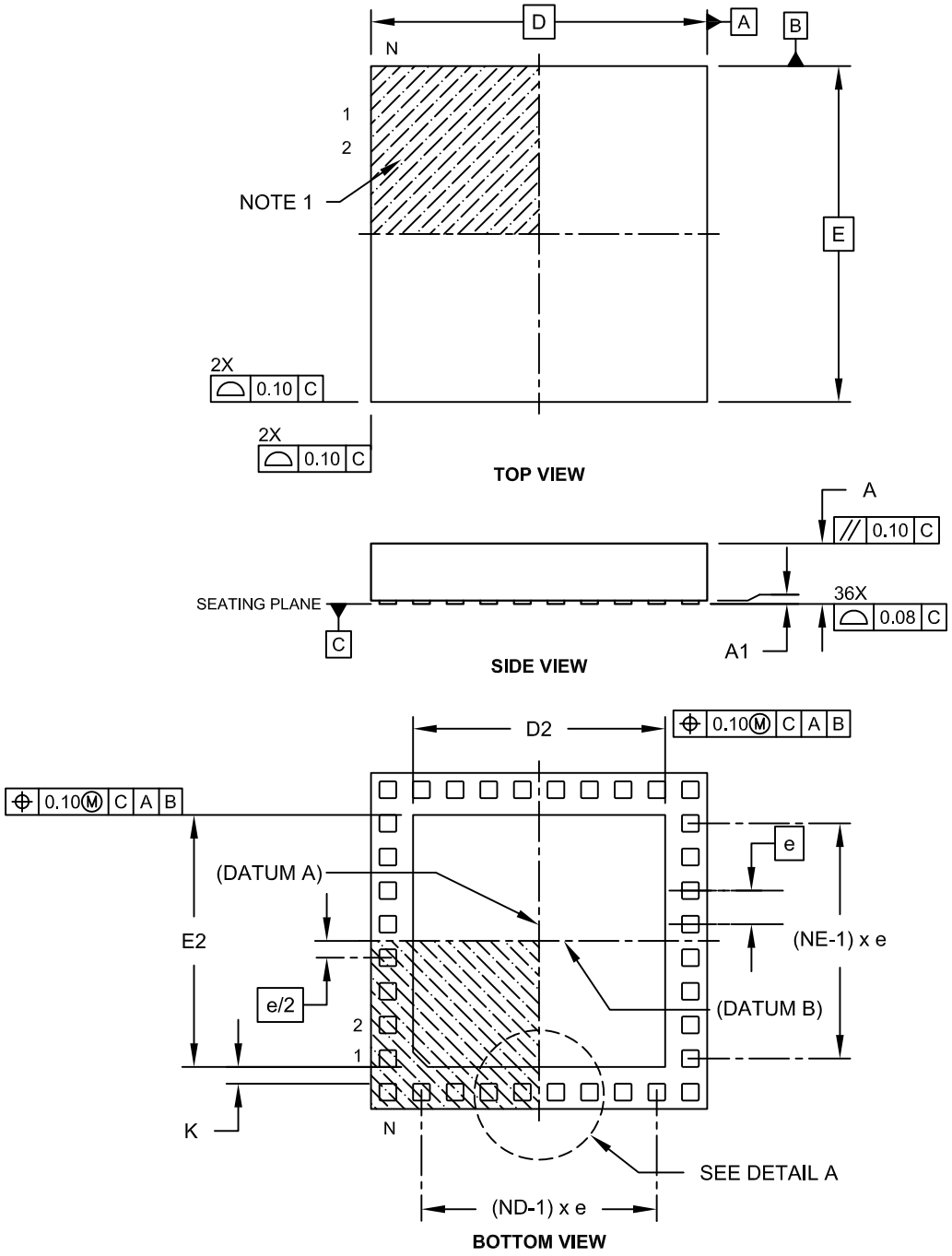


FIGURE 32-8: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-187C Sheet 1 of 2